

MEC8-DV SERIES

(0,80 mm) .0315"

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-DV

Insulator Material:
Black LCP

Contact Material:
Phosphor Bronze

Plating:
Au or Sn over

50µ" (1,27 µm) Ni

Operating Temp Range:
-55°C to +125°C

Insertion Depth:
(4,22 mm) .166" to

(5,66 mm) .223"

Current Rating:
1.8 A per pin

(6 adjacent pins powered)

Voltage Rating:
185 VAC

RoHS Compliant:
Yes

Processing:

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option
- Locking clip (Manual placement required)

Contact Samtec.

OTHER SOLUTIONS

- Right Angle
- Edge Mount

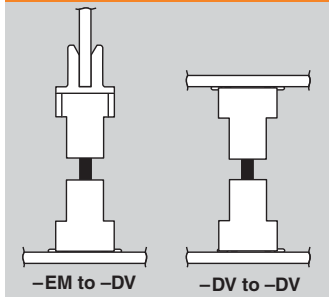
See samtec.com?MEC8-RA or samtec.com?MEC8-EM

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some sizes, styles and options are non-standard, non-returnable.

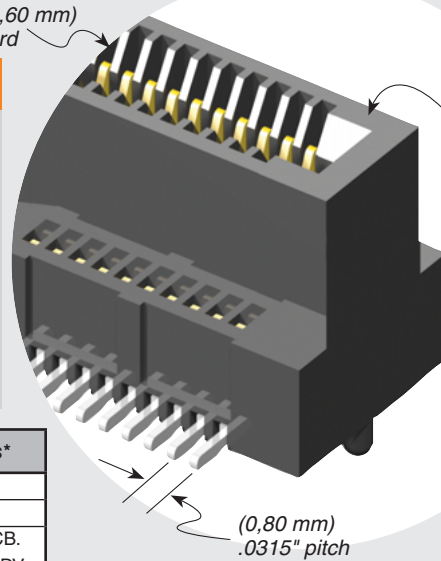
Mates with:
(1,60 mm) .062" thick cards

APPLICATIONS



Mates with (1,60 mm) .062" thick card

Variety of lead counts



MEC8-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	8.0 GHz / 16 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?MEC8-DV or contact sig@samtec.com

MEC8

1

POSITIONS PER ROW

02

PLATING OPTION

DV

OTHER OPTION

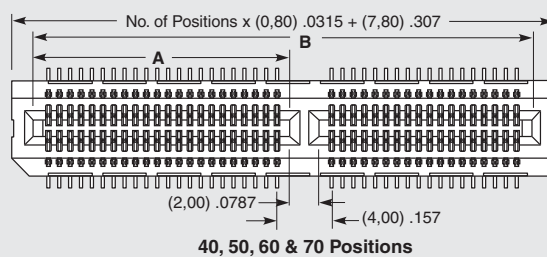
10, 20, 30, 40, 50, 60, 70

-L

= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-A
= Alignment Pin

-K
= (5,50 mm) .217" DIA Polyimide Pick & Place Pad



POSITIONS PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70	(30,90) 1.217	(60,60) 2.386

